



Introduction

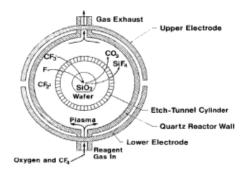
The AW-B3000 batch/barrel photoresist asher is a manual load tool designed as a flexible 13.56 MHz RF plasma photoresist removal system for high-volume wafer fabrication. The AW-B3000 is in direct response to manufacturer's concerns for Uptime, Reliability, Production-Proven technology. and low cost of ownership.

AW-B3000 Key Features

- Production-proven plasma Stripper/Asher/Descum technology.
- Φ Up to 25% Uniformity. Much lower if used with a Faraday Cage.
- Φ Consistent wafer-to-wafer uniformity.
- Φ TC Option can be used with an N2 Plasma to heat the wafers up to 170°C (Chamber) to increase ash rate.
- End-of-Process (EOP) Option automatically stops the Process after Φ all wafers are fully stripped regardless of wafer quantity or photoresist thickness.
- Φ Samples, 6" square, and up to 8" round wafers capable.
- Φ Many wafer sizes capability without hardware change.
- Ф Can handle different thickness wafer with different carriers.
- Φ New controller with PC with Advanced AW Software
- Φ Up to 5 isolated gas lines with MFC's
- Φ 13.56 MHz RF Generator. (Air-cooled Optional)
- Φ Pressure Control Throttle Valve for better process repeatability. (Optional)
- Φ MKS Baratron (Optional)
- Φ Touch screen GUI
- Φ EMO, Interlocks and Watchdog function
- GEM/SECS II (Optional)
- Made in U.S.A. Φ

AW-B3000 Applications

- Low cost production-proven plasma Asher / Descum
- Front and backside isotropic photoresist removal.
- Barrel/Batch Manual Load Process
- Descum



Production-proven Reactor



AW-B3000 Software Key Features

- Real time graphics display (GUI), process data acquisition, display, and analysis.
- Closed-loop process parameters control.
- Precise parameters profiles tailored to suit specific process requirements.
- Programmable comprehensive calibration of all subsystems from within the software. This allows faster, easier calibration, leading to enhanced process results.
- Recipe creation. It features a recipe editor to create and edit recipes to fully automate the processing of wafers inside the process chamber.
- Validation of the recipe so improper control sequences will be revealed
- Storage of multiple recipes, process data and calibration files so that process and calibration results can be maintained and compared over time
- Passwords provide security for the system, recipe editing, diagnostics, calibration and setup functions
- Simple and easy to use menu screen which allow a process cycle to be easily defined and executed.
- Troubleshooting features which allows engineers and service personnel to activate individual subassemblies and functions. More I/O, AD/DA "exposure".
- DB-25F parallel (printer) port. The computer interfaces to the Allwin21 system with only one cable: the control interface cable.
- The control board inside the machine that translates the computer commands to control the machine has a watchdog timer. If this board looses communication with the control software, it will shut down all processes and halt the system until communication is restored.
- GEM/SEC II function (Optional).
- Advanced Allwin21 EOP function (Optional)

AW-B3000 Specifications

- Wafer Size: Sample to 200mm Capability. Multiple wafer size without hardware change
- ❖ High Throughput: Up to 75 WPH. Process Dependent.
- Temperature: Only TC Option can be used for N2 plasma to heat the substrates up to 170°C.
- Gas Lines: Up to 5 isolated gas lines with MFCs.
- Asher Rate: 0-0.1u/min. positive PR; >0.2u/min. negative PR. Slower if Faraday Cage is used
- Uniformity: Up to 25%. Much lower with Faraday Cage.
- Particulate: <0.05 /cm2 (0.03um or greater)</p>
- Damage: Low damage with Faraday Cage.
- ❖ Selectivity: >1000:1
- ❖ MTBF/MTTA/MTTR: 450 Hours/100 Hours/3.5 Hours or Better.
- 95% uptime
 - * Contact Allwin21 sales for other applications and specifications

AW-B3000 Configuration

- Main Body with wires
- Control Box
- Pentium Class PC with AW Software
- Keyboard, Mouse, USB with SW backup and Cables
- Main Control PCB and DC
- Transformer, Circuit Breaker, Contactor
- 1-5 Isolated Gas Lines w/ Pneumatic Valve and MFC
- Purge has manual regulator in controller box to control speed.
- Quartz Chamber: Dia 12" x Depth 23";
- RF Match Network Integrated in the Main Body of tool.
- Chamber Door with quartz plate in the Main Body.
- Gas and vacuum lines Connections in the Main Body
- 13.56MHz RF Generator (Air-Cooled is Optional)
 300W; 2 600W; 3 1000W; 4 1200W
- Lamp tower alarm with buzzer
- Main Vacuum Valve
- MKS Baratron
- Throttle Valve
- Front EMO, Interlocks
- 15-inch Touch Screen GUI



Main Menu Screen

Options:

- ♦ End-of-Process (EOP) function.
- Throttle Valve for pressure control.
- ◆ Air-cooled RF Generator.
- ◆ GEM/SECS II function (Software)
- ◆ Thermocouple for Chamber Temperature
- ♦ Vacuum Pump